

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IAUZ18N10S5L420	**Issued**	4. February 2020
MA#	MA005346307		
Package	PG-TSDSON-8-32	**Weight***	35.22 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.230	0.65	0.65	6523	6523
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		88	
	non noble metal	zinc	7440-66-6	0.012	0.04		353	
	non noble metal	iron	7439-89-6	0.249	0.71		7064	
	non noble metal	copper	7440-50-8	10.102	28.68	29.44	286831	294336
wire	noble metal	gold	7440-57-5	0.030	0.09	0.09	859	859
encapsulation	organic material	carbon black	1333-86-4	0.037	0.11		1064	
	plastics	epoxy resin	-	1.930	5.48		54803	
	inorganic material	silicondioxide	60676-86-0	16.772	47.60	53.19	476198	532065
leadfinish	non noble metal	tin	7440-31-5	0.400	1.14	1.14	11365	11365
plating	noble metal	silver	7440-22-4	0.086	0.24	0.24	2431	2431
solder	non noble metal	tin	7440-31-5	0.008	0.02		213	
	noble metal	silver	7440-22-4	0.009	0.03		267	
	non noble metal	lead	7439-92-1	0.359	1.02	1.07	10189	10669
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001	0.00		26	
	non noble metal	zinc	7440-66-6	0.004	0.01		103	
	non noble metal	iron	7439-89-6	0.073	0.21		2068	
	non noble metal	copper	7440-50-8	2.958	8.40	8.62	83974	86171
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		17	
	non noble metal	zinc	7440-66-6	0.002	0.01		67	
	non noble metal	iron	7439-89-6	0.047	0.13		1334	
	non noble metal	copper	7440-50-8	1.908	5.42	5.56	54163	55581
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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